

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7517620

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the DATE OF SIGNATURE FOR THE 1ST INVENTOR previously recorded on Reel 054030 Frame 0432. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
DONG WON SON	09/25/2020
JONG HO SHIN	09/25/2020
SUNG JAE LIM	09/25/2020
SUNG HO CHOI	09/25/2020
BYEONGHOON KIM	09/25/2020
CHANGOH KIM	10/08/2020
SUNGWON CHO	10/06/2020
KYOUNGHEE PARK	10/07/2020
RECEIVING PARTY DATA	
Name:	STATS CHIPPAK PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	11355452
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	480-499-9400
Email:	main@plgaz.com
Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES, P.C.
Address Line 1:	123 W. CHANDLER HEIGHTS ROAD, #12535
Address Line 4:	CHANDLER, ARIZONA 85248
ATTORNEY DOCKET NUMBER:	2515.0524 CIP
NAME OF SUBMITTER:	LISA ROSSETTI

SIGNATURE:	/Lisa Rossetti/
DATE SIGNED:	09/01/2022
Total Attachments: 11 source=17068482NOTICE#page1.tif source=17068482NOTICE#page2.tif source=17068482NOTICE#page3.tif source=17068482ASSIGNMENT#page1.tif source=17068482ASSIGNMENT#page2.tif source=17068482ASSIGNMENT#page3.tif source=17068482ASSIGNMENT#page4.tif source=17068482ASSIGNMENT#page5.tif source=17068482ASSIGNMENT#page6.tif source=17068482ASSIGNMENT#page7.tif source=17068482ASSIGNMENT#page8.tif	

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6345847

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DONG WON SON	<u>09/25/2020</u> 09/24/2020
JONG HO SHIN	09/25/2020
SUNG JAE LIM	09/25/2020
SUNG HO CHOI	09/25/2020
BYEONGHOON KIM	09/25/2020
CHANGOH KIM	10/08/2020
SUNGWON CHO	10/06/2020
KYOUNGHEE PARK	10/07/2020
RECEIVING PARTY DATA	
Name:	STATS CHIPPAK PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17068482
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	480-499-9400
Email:	main@plgaz.com
Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES
Address Line 1:	123 W. CHANDLER HEIGHTS ROAD, #12535
Address Line 4:	CHANDLER, ARIZONA 85248
ATTORNEY DOCKET NUMBER:	2515.0524 CIP
NAME OF SUBMITTER:	LISA ROSSETTI
SIGNATURE:	/Lisa Rossetti/

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, DONG WON SON of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

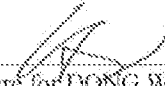
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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

28 Sep 2020
Date Signed


Signature for DONG WON SON

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JONG HO SHIN of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

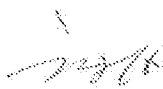
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9.25.2020
Date Signed


Signature for JONG HO SHIN

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG JAE LIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 251S.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

2020.9.25
Date Signed

SJL
Signature for SUNG JAE LIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG HO CHOI of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020 9 25
Date Signed


Signature for SUNG HO CHOI

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYEONGHOON KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

2020. 09. 25
Date Signed


Signature for BYEONGHOON KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, CHANGOH KIM of Incheon, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

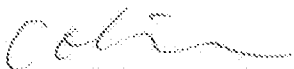
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20.10.08
Date Signed


Signature for CHANGOH KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNGWON CHO of Seoul, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 10. 6

Date Signed



Signature for SUNGWON CHO

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYOUNGHEE PARK of Seoul, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

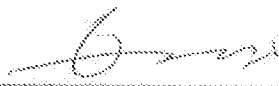
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2020.10.07
Date Signed


Signature for KYOUNGHEE PARK